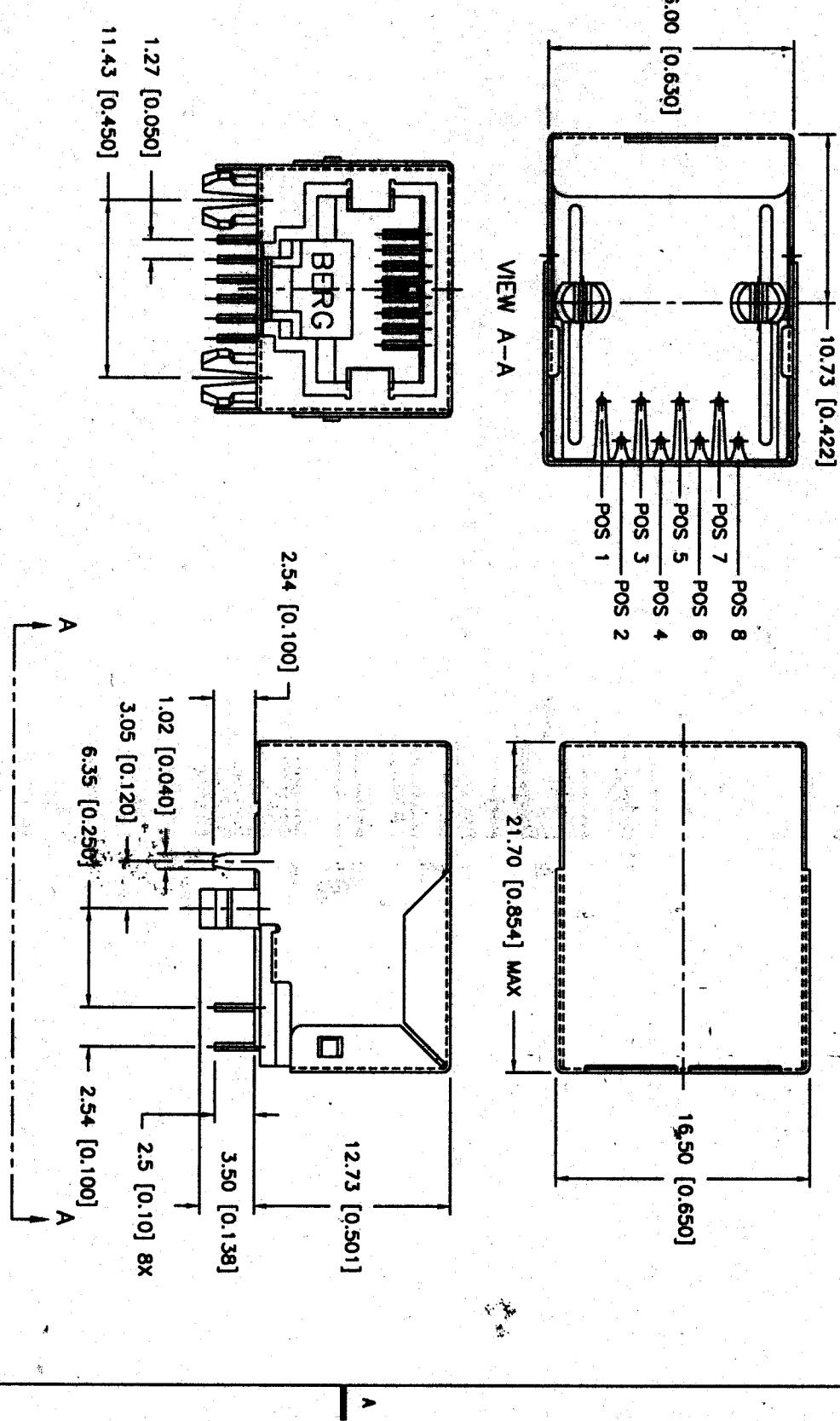


PRODUCT NO.
73438-X01LF

1 | 2

3 |

4 |



PART' code		Reference unless otherwise specified.		CUSTOMER COPY	FCI	www.fci.com
Nr	scn no	dr	date			
A	V70430	GH	3/5/97	floor	1.12.3/2002.01	projection
B	V70452	GH	8/27/97	AT&T 601/2000	0.22	R/A, 8 POS. L.P., SNAP PEG, SHIELDED MOD JACK ASSEMBLY
C	V70688	GH	7/10/97	orange	0.22	SHIELDED MOD JACK ASSEMBLY
D	V71593	GH	1/18/97	GH/AL	0.22	SHIELDED MOD JACK ASSEMBLY
E	V71260	IP	1/18/97	orange	0.22	SHIELDED MOD JACK ASSEMBLY
F	73438-C01	MKT	4/13/97	blue/white	0.22	SHIELDED MOD JACK ASSEMBLY
Print revision	1	Print revision	1	1/1	A	73438
Print sheet	1	Print sheet	1			1-1-2

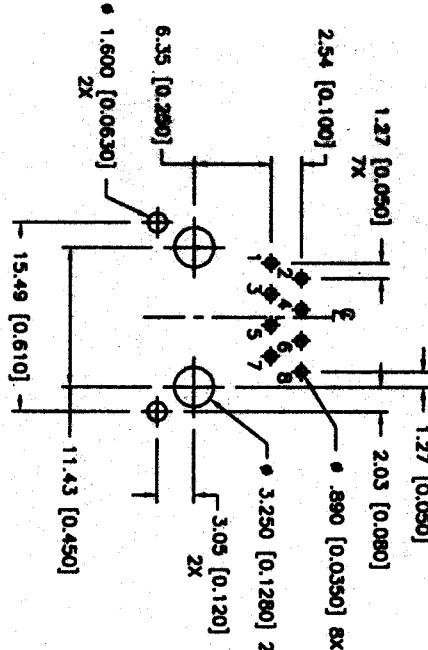
AC/AN

PDM: Rev:F

STATUS:Released 22526 4/10/2007 Mar 10, 2007

PRODUCT NO. 73438-X011E

PLATING CODE X	PLATING (10)
0	.76µm/30µ" G.X.T.
3	.76µm/30µ" GOLD
5	1.27µm/50µ" GOLD



.51 [0.020] -
TOP OF PCB TO
BOTTOM OF OPENING

RECOMMENDED PANEL OPENING
SCALE: 2/1

500: 1/2

1. RECOMMENDED P.C.B. THICKNESS 1.60 [0.062]
2. HOUSING MATL: ZYTEL HTNFR52G30L-BK337, COLOR BLACK, UL94V-1
3. CONTACTS: PHOS BRONZE ALLOY, # 0.460 [0.0181] ROUND WIRE, SEE TABLE FOR PLATING.
4. SHIELDING MATL: .25 [0.010] THICK, BRASS ALLOY, PLATING: TIN, 2.03-.381 μ /80-.150 μ THK.
5. ALL DIMENSIONS IN MILLIMETERS AND INCHES.
6. PRODUCT TO BE PACKAGED IN TUBES.
7. ADD LF SUFFIX AT THE END OF PART NUMBER FOR LEAD FREE OPTION.
8. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 15 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.5mm MINIMUM THICK CIRCUIT BOARD. SEE APPLICATION NOTES/PROCEDURES IF THEY ARE AVAILABLE.
9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008.
10. PLATING OPTIONS:
MAY BE EITHER GOLD OR GXT PLATED AT MANUFACTURER'S OPTION